Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A method of manufacturing an integrated circuit, comprising:

providing an amorphous semiconductor material including germanium above a bulk substrate of semiconductor material;

laser annealing the amorphous semiconductor material to form a single crystalline semiconductor layer containing germanium;

doping the single crystalline semiconductor layer and the substrate at a source location and a drain location to form a source region and a drain region, whereby a channel region between the source region and the drain region includes a thin semiconductor germanium region; and

siliciding the source region and the drain region to form a silicide layer, the silicide layer extending into the substrate.

2. (Original) The method of claim 1 further comprising:

before the doping step, providing a cap layer above the amorphous semiconductor layer.

3. (Original) The method of claim 2 further comprising:

after the providing a cap layer step, providing a gate structure between the source location and the drain location.

4. (Original) The method of claim 3, wherein the cap layer is an amorphous semiconductor layer.

5. (Original) The method of claim 4, further comprising:

before the doping step, annealing the cap layer.

6. (Original) The method of claim 4, wherein the amorphous semiconductor layer includes silicon.

7. (Original)The method of claim 1, wherein the bulk substrate includes single crystalline silicon.

8. (Previously Presented) The method of claim 1, wherein the amorphous semiconductor material includes silicon germanium.

9. (Previously Presented) The method of claim 7, wherein the amorphous semiconductor material includes silicon germanium.

10. (Original) The method of claim 9, wherein the annealing step takes place at a temperature sufficient to melt the amorphous semiconductor layer and is below the melting temperature of the substrate.

11. (Previously Presented) The method of claim 1, further comprising:

providing a second amorphous semiconductor material above the amorphous semiconductor material including germanium after the laser annealing step;

performing another laser annealing step to form a second single crystalline semiconductive layer from the second amorphous semiconductor material; and

wherein the siliciding step forms the silicide layer so that the depth of the silicided layer is deeper than the second single crystalline semiconductor layer.

12. (Previously Presented) A method of manufacturing an ultra-large scale integrated circuit including a transistor, the method comprising steps of:

depositing an amorphous silicon germanium material above a top surface of a semiconductor substrate;

first annealing the amorphous silicon germanium material;

depositing an amorphous silicon material above the silicon germanium material;

second annealing the amorphous silicon material; and

providing a source region and a drain region for the transistor, the source region and the drain region being deeper than a combined thickness of the silicon germanium material and the silicon material.

13. (Original) The method of claim 12, further comprising:

providing a gate structure before providing a source region and a drain region step.

14. (Original) The method of claim 12, further comprising:

providing an oxide layer over the silicon material after the second annealing step.

15. (Original) The method of claim 12, wherein the silicon germanium material is a single crystalline layer after the first annealing step.

16. (Original) The method of claim 12, wherein the silicon material is a single crystalline layer after the second annealing step.

17. (Original) The method of claim 12, wherein the silicon material is 100-150Å thick.

18. (Original) The method of claim 12, wherein the annealing temperature for the first and second annealing steps is at or above 1100°C and below 1400°C.

19. (Currently Amended) A process of forming a transistor with a silicon germanium channel region, the process comprising:

depositing a thin amorphous silicon germanium material above a top surface of a semiconductor substrate;

annealing the silicon germanium material to form single crystalline silicon germanium material;

depositing a thin amorphous silicon material above the single crystalline silicon germanium material;

annealing the silicon material to form single crystalline silicon material; ~~and~~

providing a source region and a drain region for the transistor, the source region and the drain region extending into the substrate; and

forming a conductive region in the source region or the drain region.

20. (Original) The process of claim 19, wherein the silicon germanium material is 200-500Å thick.

21. (Original) The process of claim 20, wherein the silicon material is 100-150Å thick.

22. (Original) The process of claim 19, wherein the annealing steps are excimer laser annealing steps.

23. (Original) The process of claim 22, wherein the excimer laser annealing steps use a wavelength of 308 nanometers.

24. (Original) The process of claim 23, the source and drain regions each including an extension.

25.-26. (Cancelled)

27. (Currently Amended) A method of manufacturing a transistor comprising a source and drain region and a channel region, the source and drain regions being at least partially disposed in a bulk semiconductor substrate, the channel region being disposed between the source and drain regions, the channel region including a silicon germanium layer and a silicon cap layer, the method comprising:

providing an amorphous semiconductor material including germanium above a bulk substrate of semiconductor material;

providing an amorphous silicon layer above the amorphous semiconductor material;

annealing the amorphous semiconductor material and the amorphous silicon layer to form the silicon germanium layer and the silicon cap layer, the silicon germanium layer and the silicon cap layer are single crystalline; ~~and~~

doping the single crystalline semiconductor layer and the substrate at a source location and a drain location to form a source region and a drain region, whereby the channel region between the source region and the drain region includes at least a portion of the semiconductor germanium layer covered by the silicon cap layer; and

forming a conductive region in the source region or the drain region.

28. (Currently Amended) The method of claim 27, wherein the source and drain regions are silicided in the forming step to relieve any effect of germanium in the source and drain regions.

29. (Previously Presented) The method of claim 12 further comprising:

siliciding the source and the drain region to form a silicide layer, wherein the silicide layer extends deeper than the combined thickness.